

WHAT IS CLAIMED IS:

1. A heat-resistant insulating film, comprising:
a pattern profile corresponding to a structure with
5 geometries including a convex or concave portion, the pattern
profile being formed by three-dimensional forming for fitting
onto the structure.
2. The heat-resistant insulating film according to claim 1,
10 wherein a material of the film is a polyimide.
3. The heat-resistant insulating film according to claim 1,
wherein the pattern profile includes an uneven profile having
a ratio of a depth to an opening width less than or equal to
15 two.
4. The heat-resistant insulating film according to claim 1,
wherein the structure is a circuit board mounted with electronic
components on the board.
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5. The heat-resistant insulating film according to claim 1,
wherein the three-dimensional forming is vacuum/compressed air
forming.
- 25 6. The heat-resistant insulating film according to claim 1,
wherein the three-dimensional forming is pressure forming using
a die.

7. A method for insulating a structure to be insulated, comprising:

forming a heat-resistant insulating film into a pattern
5 profile corresponding to a surface to be insulated of the structure with geometries including a convex or concave portion by three-dimensional forming; and

covering the surface to be insulated with the heat-resistant insulating film.

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8. The method according to claim 7, wherein a material of the film is a polyimide.

9. The method according to claim 7, wherein the pattern
15 profile includes an uneven profile having a ratio of a depth to an opening width less than or equal to two.

10. The method according to claim 7, wherein the structure
is a circuit board mounted with electronic components on the
20 board.

11. The method according to claim 7, wherein the three-dimensional forming is vacuum/compressed air forming.

25 12. The method according to claim 7, wherein the three-dimensional forming is pressure forming using a die.